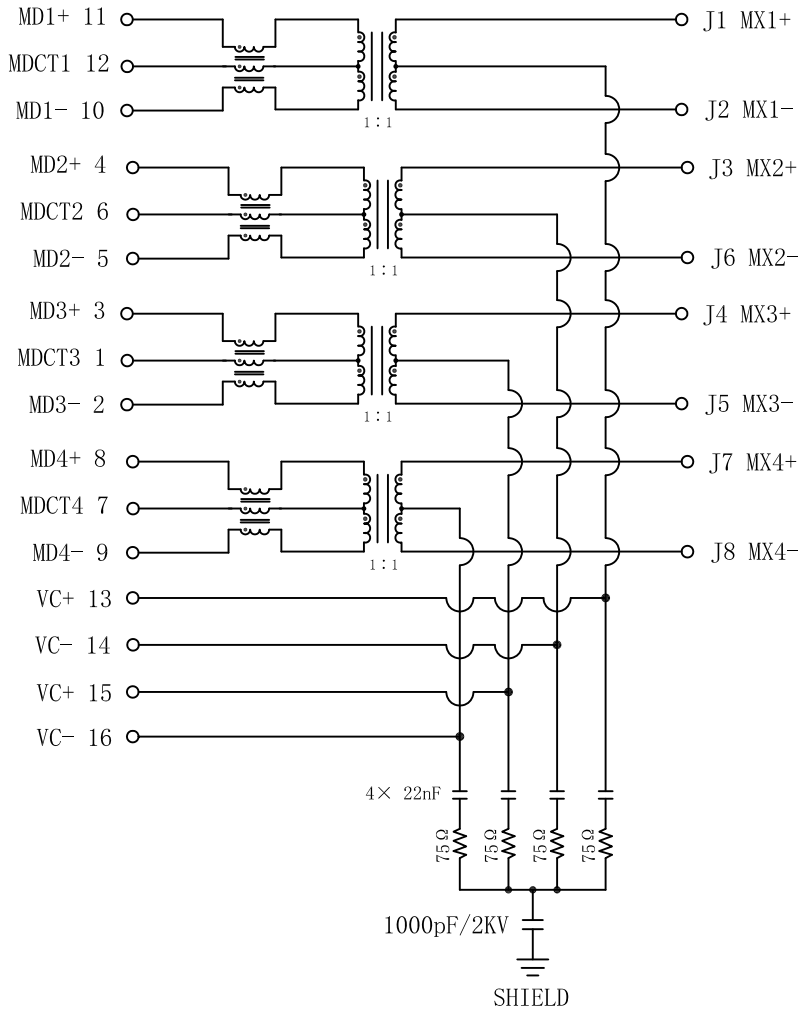


Schematic :

REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		2010-11-19	

PC BOARD CONNECTIONS



Electrical Specifications @25°C

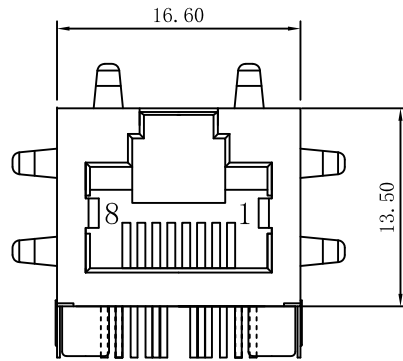
- Inductance: 350uH Min @100KHz, 0.1V, 8mA DC Bias.
- Turns Ratio ($\pm 2\%$):
Pri : Sec = 1CT : 1CT
- Insertion Loss:
1-100MHz: -1.0dB Max
- Return Loss (load 100 Ω):
1-30MHz: -18dB Min
30-60MHz: -16dB Min
60-80MHz: -12dB Min
80-100MHz: -10dB Min
- Crosstalk:
1-100MHz: -30dB Min
- Common Mode Rejection:
1-100MHz: -30dB Min
- Balanced DC Line Current:
350mA Max @57VDC Continuous
500mA Max @57VDC For 200 Milliseconds.
- Hipot: 1500Vrms Min @60Hz
- Operating Temperature: 0°C ~ 70°C.



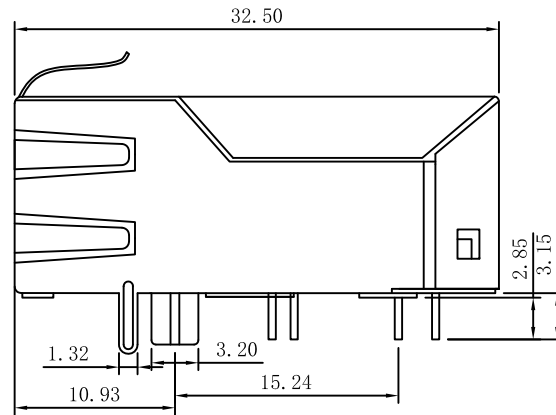
X:X	± 0.30	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED	
X:XX	± 0.25	CHKD:	TITLE: RJ45 Connector with 1000 Base-T Integrated Magnetics For PoE Application	
X:XXX	± 0.05	DR: TOM		
ANGLES	$\pm 1^\circ$	UNIT: mm	PART NO.: LPJK2064CNL	
	SCALE: 2/1	SHEET: 1/2	REV: A	DWG NO.: LP10111917

Mechanical :

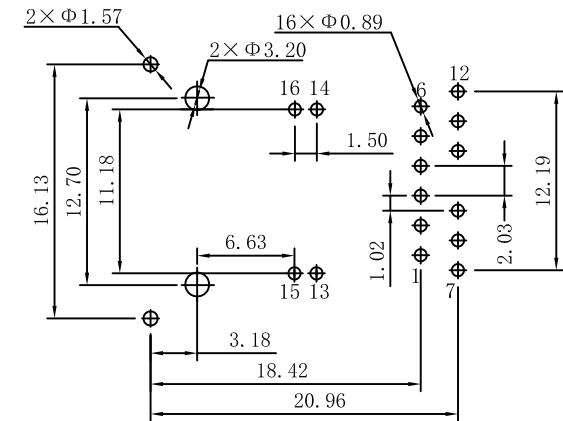
REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		2010-11-19	



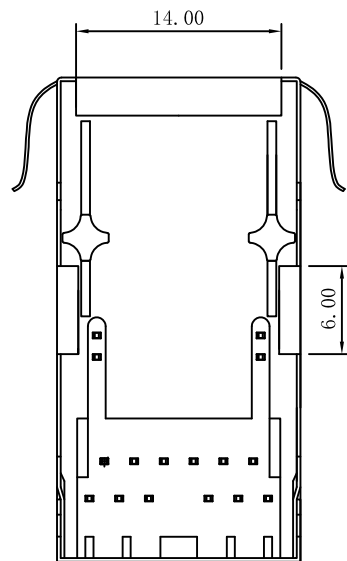
Front Side View



Left Side View



Suggested PCB Layout (Top View)



Bottom Side View



Top Side View

NOTES:

1. Designed to support application, such as SOHO (ADSL modems), LAN-ON-Motherboard (LOM), hub and Switches.
2. Meets IEEE 802.3af specification
3. Connector Materials:
 Housing Material: Thermoplastic PBT+30%G.F UL94V-0
 Contact Material: Phosphor Bronze C5210R-EH Thickness=0.35mm
 Pins: Brass C2680R-H Thickness=0.35mm
 Shield: Copper alloy Brass H65Y Thickness=0.2mm
 Contact plating: Gold 6 micro-inches min. In contact area.
4. Wave solder tip temperature: 265°C Max, 5 Sec Max

X:X	±0.30	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED	
X:XX	±0.25	CHKD:	TITLE: RJ45 Connector with 1000 Base-T Integrated Magnetics For PoE Application	
X:XXX	±0.05	DR: TOM	PART NO.: LPJK2064CNL	
ANGLES	±1°	UNIT: mm	REV: A	
	SCALE: 2/1	SHEET: 2/2	DWG NO.:	LP10111917